

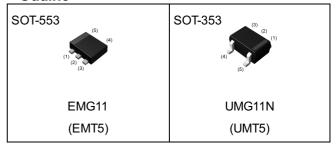
## Emitter common (dual digital transistors

Parameter	DTr1 and DTr2
V <sub>CC</sub>	50V
$I_{C(MAX.)}$	100mA
R <sub>1</sub>	2.2kΩ
R <sub>2</sub>	47kΩ

#### Features

- 1)Two DTC123J chips in a EMT or UMT package.
- 2) Mounting cost and area can be cut in half.

## Outline



#### •Inner circuit

(1) DTr1 IN(Base) (5) (4)
(2) DTr1 / DTr2
GND(Emitter) (3) DTr2 IN(Base)
(4) DTr2 OUT(Collector) (5) DTr1 OUT(Collector)

(1)

(2)

# Application

INVERTER, INTERFACE, DRIVER

# Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
EMG11	SOT-553 (EMT5)	1616	T2R	180	8	8000	G11
UMG11N	SOT-353 (UMT5)	2021	TR	180	8	3000	G11

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Parameter		Symbol	Values	Unit
Supply voltage		V <sub>CC</sub>	50	V
Input voltage		V <sub>IN</sub>	-5 to 12	V
Output current		Io	100	mA
Collector current		I <sub>C(MAX)</sub> *1	100	mA
Davis a dia sia atta a	EMG11	P <sub>D</sub> *2*3	150	::::\\//T- t-
Power dissipation	UMG11N	P <sub>D</sub> *2*3	150	mW/Total
Junction temperature		Tj	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Downwater	Cymahal	Conditions	Values			l leit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
lanut valtaga	$V_{l(off)}$	$V_{CC} = 5V, I_{O} = 100 \mu A$	-	-	0.5	\ <u>'</u>	
Input voltage	V <sub>I(on)</sub>	$V_O = 0.3V$ , $I_O = 5mA$	1.1	-	-	V	
Output voltage	V <sub>O(on)</sub>	I <sub>O</sub> = 5mA, I <sub>I</sub> = 0.25mA	-	100	300	mV	
Input current	I <sub>I</sub>	V <sub>I</sub> = 5V	-	-	3.6	mA	
Output current	I <sub>O(off)</sub>	V <sub>CC</sub> = 50V, V <sub>I</sub> = 0V	-	-	500	nA	
DC current gain	G <sub>I</sub>	V <sub>O</sub> = 5V, I <sub>O</sub> = 10mA	80	-	-	-	
Input resistance	R <sub>1</sub>	-	1.54	2.2	2.86	kΩ	
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	-	17	21	26	•	
Transition frequency	f <sub>T</sub> *1	$V_{CE} = 10V, I_{E} = -5mA,$ f = 100MHz	1	250	-	MHz	

<sup>\*1</sup> Characteristics of built-in transistor.

<sup>\*2</sup> Each terminal mounted on a reference land.

<sup>\*3 120</sup>mW per element must not be exceeded.

# ● Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Fig.1 Input Voltage vs. Output Current (ON Characteristics)

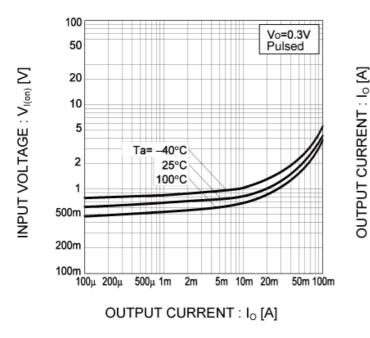


Fig.2 Output Current vs. Input Voltage (OFF Characteristics)

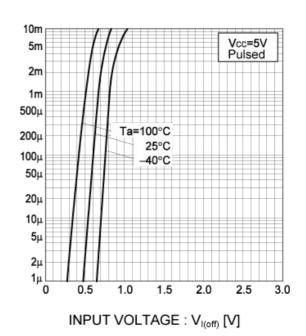


Fig.3 Output Current vs. Output Voltage

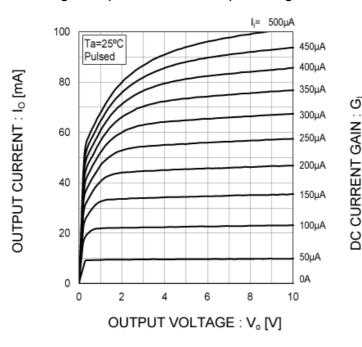
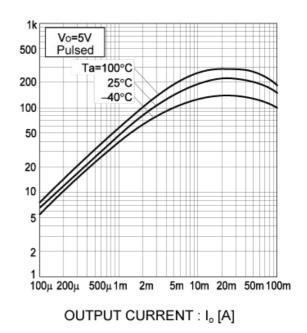


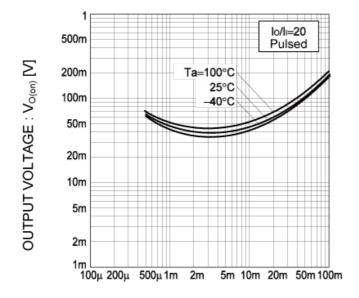
Fig.4 DC Current Gain vs. Output Current



# ● Electrical characteristic curves (T<sub>a</sub> = 25°C)

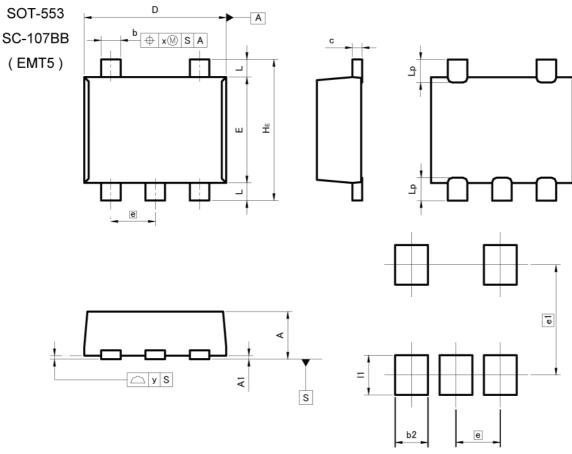
<For DTr1 and DTr2 in common>

Fig.5 Output Voltage vs. Output Current



OUTPUT CURRENT: Io [A]

# Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

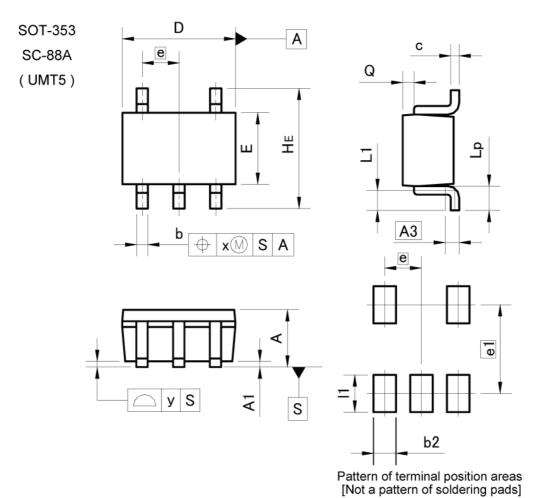
DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
е	0.50		0.020	
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	_	0.35	-	0.014
х	_	0.10	_	0.004
У	_	0.10	_	0.004

DIM	MILIMETERS		INCHES	
DIM MIN		MAX	MIN	MAX
b2	-	0.37	_	0.015
e1	1.25		0.0	49
- 11	_	0.45	-	0.018

Dimension in mm/inches



# Dimensions



DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.	0.65		26
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
Х	_	0.10	-	0.004
У	-	0.10	-	0.004

DIM	MILIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
b2	- 1	0.40	-	0.016	
e1	1.55		0.0	61	
11	-	0.65	-	0.026	

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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